

POS	SPECIFICATION	DOCUMENT#	REMARK
1	Valid for ED-type product family with or without TIM	DRW 0009	Outline drawing ED-type products
2	RoHS compliant		YES
3	Weight		350 g ± 20 g

POS	CONSTRUCTION ELEMENT	MATERIAL GROUP	MATERIALS	CAS-NR IF APPLICABLE	AVERAGE MASS <sup>1</sup> IN %	COMMENT
1	Chip	Inorganic material	Silicon	7440-21-3	0.2	
2	Baseplate, substrate, incl. metallization	Non noble metal	Copper	7440-50-8	61	
3		Inorganic	Aluminum oxide	1344-28-1	1.6	
4		Non noble metal	Tin	7440-31-5	1.9	
5	Wire	Noble metal	Silver	7440-22-4		Traces
6		Non noble metal	Nickel	7440-02-0	0.1	Traces
7	Encapsulation	Non noble metal	Aluminum	7429-90-5	0.3	
8		Non noble metal	Copper	7440-50-8	0.1	
9	Housing	Polymer	Silicone gel		9.8	
10		Polymer	Silicon glue		0.3	
11	Power & signal terminals incl plating, nuts, and rivets	Polymer	PBT		10.1	
12		Inorganic material	Glas fiber		4.3	
13	SMD (thermistors)	Non noble metal	Copper	7440-50-8	6.9	
14		Ferrous metal	Steel		2.8	
15	Total %	Non noble metal	Nickel	7440-02-0		Traces
16		Non noble metal	Zinc	7440-66-6	0.5	
17		Non noble metal	Tin	7440-31-5		Traces
18		Inorganic material				RoHS compliant
19					<b>100</b>	Total %

**REMARKS**

- The information provided is the full declaration of all materials present in SwissSEM product of ED-type product family above a threshold of 0.1% or 1000 ppm.
- All information is according to the best of our knowledge and subject to change at any time for required changes.
- SwissSEM products are not classified as “hazardous substances” according to the definition of EU directive 67/548/EC and do hence not require a Material Safety Datasheet.

DATE	AUTHOR	REMARK
April 14th, 2022	SM	Initial Version

<sup>1</sup> Related to component weight

AUTHOR	CHECKED	RELEASED
PL	VP Application and Testing	VP Supply and Quality